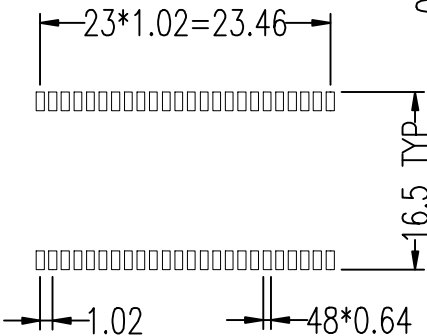
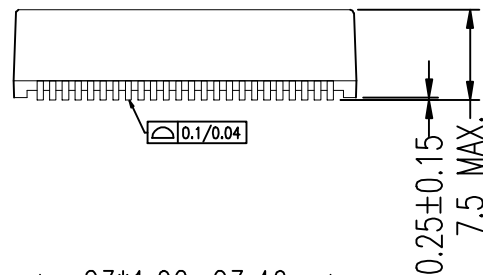
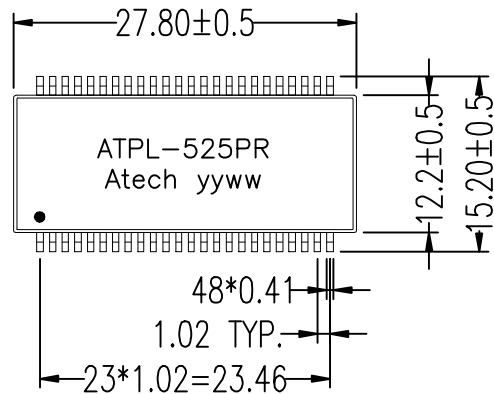
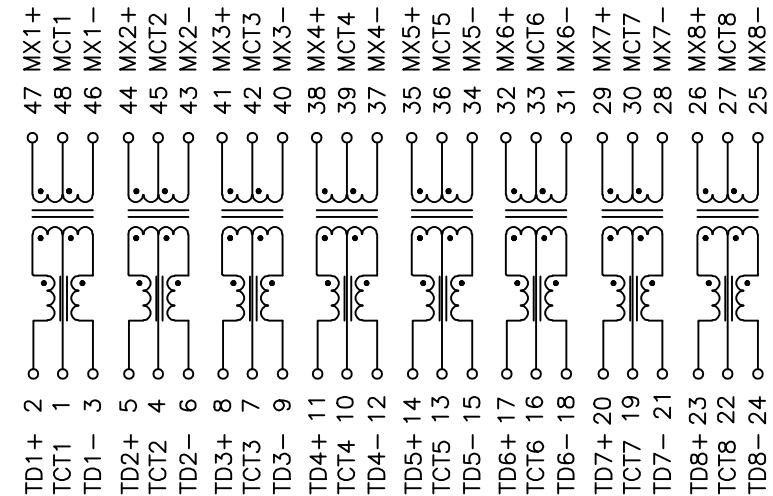
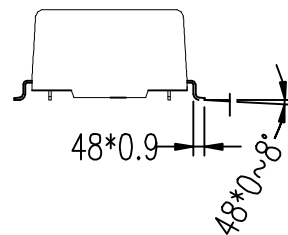




SUGGESTED PCB LAYOUT



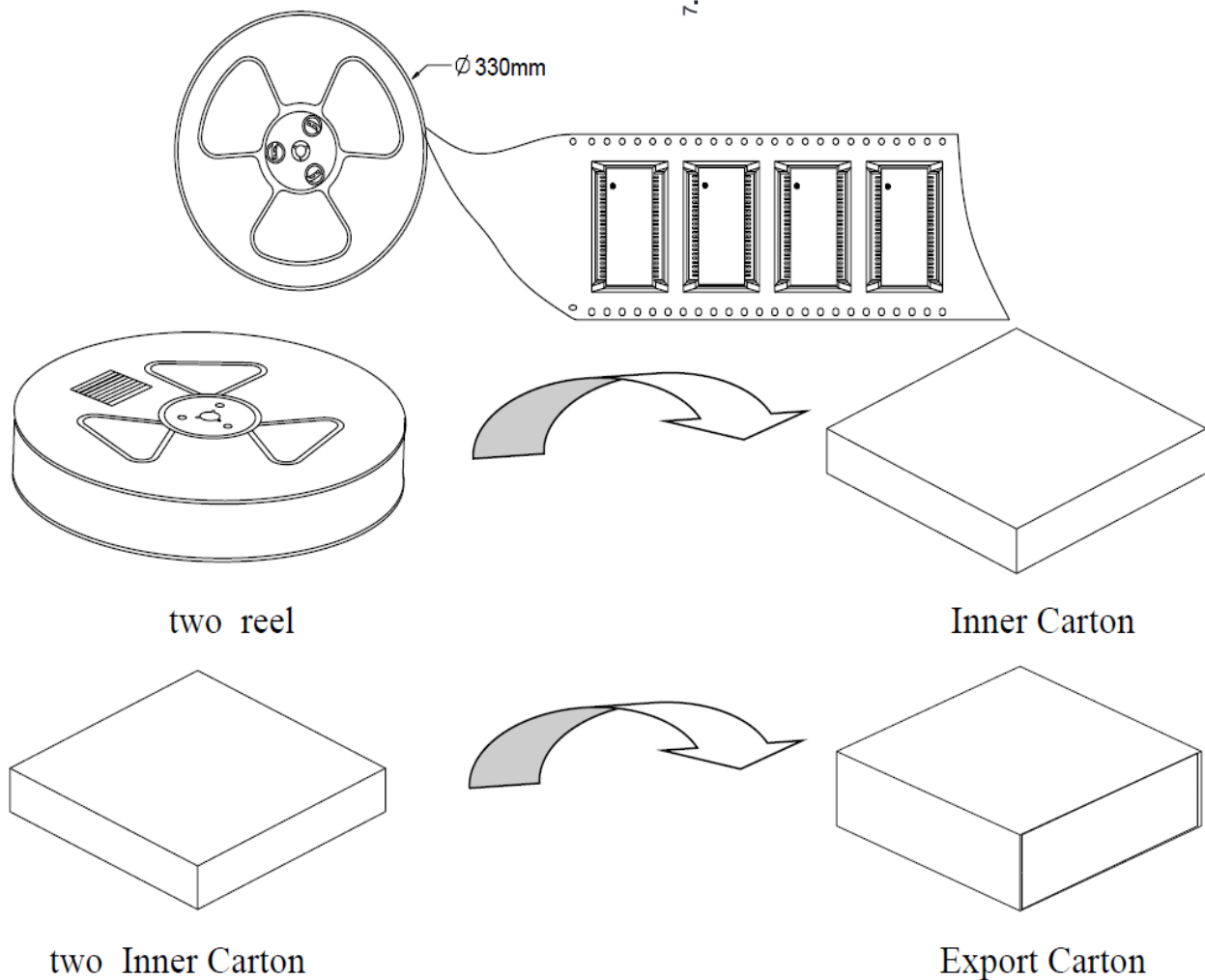
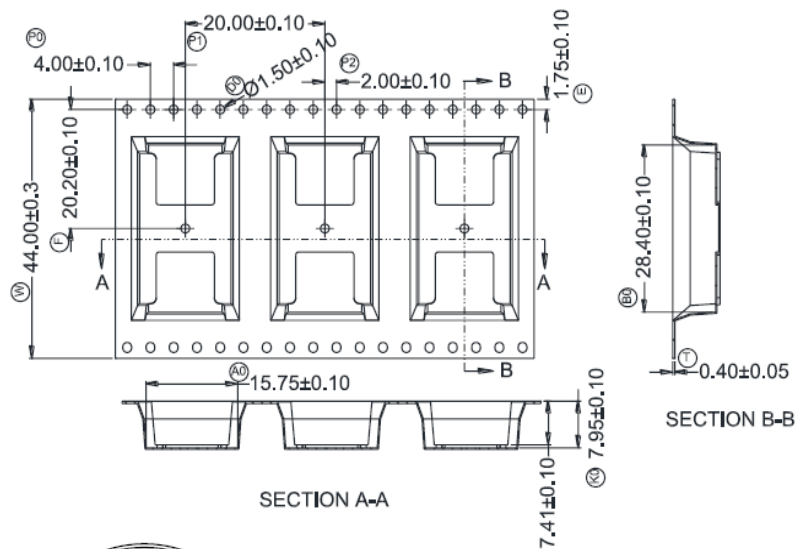
ELECTRICAL CHARACTERISTICS @25°C :

1. INSULATION HI-POT(PRI./SEC.) : 1500Vrms, 1mA, 60SEC
2. TURN RATIO (±5%) : TX = 1CT : 1CT , RX = 1CT : 1CT
3. OCL : 350uH MIN. @100kHz, 0.1V WITH 8mA DC BIAS
4. LEAKAGE INDUCTANCE : 0.5uH MAX @100kHz, 0.1V
5. DCR : 1400mΩ MAX.
6. INSERTION LOSS : -1.2dB MAX.(@0.5-1MHz)
-0.2-0.002*f^1.4 dB MAX(@1-125MHz)
7. RETURN LOSS : -16 dB MIN.(@1-40MHz)
-10+20*log (f/80) dB MIN.(@40.1-100MHz)
8. CROSS TALK : 1-100MHz : -30dB MIN.
9. CMRR : 1-100MHz : -30dB MIN.
10. OPERATING TEMPERATURE RANGE : -40°C~+85°C
11. IEEE802.3at COMPLIANT PERFORMANCE
---1200mA Current capability
12. STORAGE TEMPERATURE : -40°C to +125°C
13. RoHS COMPLIANT

UNLESS OTHERWISE SPECIFIED ALL TOLERANCES ARE XX.XX±0.25 0.XX±0.05

								TITLE 10/100/1000 BASE-T PoE++ TRANSFORMER	
								DWG. NO. ATPL-525PR	
	RELEASE	08/31/2018	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY		SHEET 1 of 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE	P/N:	DRAW	
REVISIONS						08/31/18			SHIRLEY

3. Package:



Package Quantity:

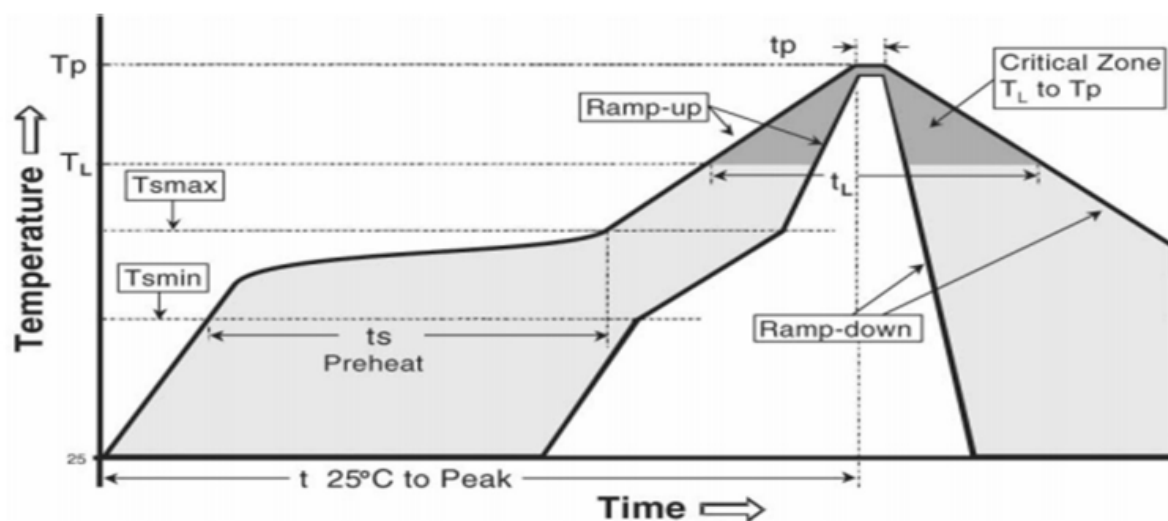
One Reel=350Pcs

One Inner Carton=350*2=700Pcs

One Export Carton=700*2=1400Pcs

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to T _p)	3°C/second max	3°C/second max
Preheat Temperature Min (T _{sm}) Temperature Min (T _{sm}) Time (T _{sm} to T _{sm}) (t _s)	100°C 150°C 60-120seconds	150°C 200°C 60-180seconds
Time maintained above Temperature (T _L) Time (t _L)	183°C 60-150seconds	217°C 60-150seconds
Peak Temperature (T _p)	225°C	260°C
Time within 5°C of actual Peak Temperature (T _p) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max